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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

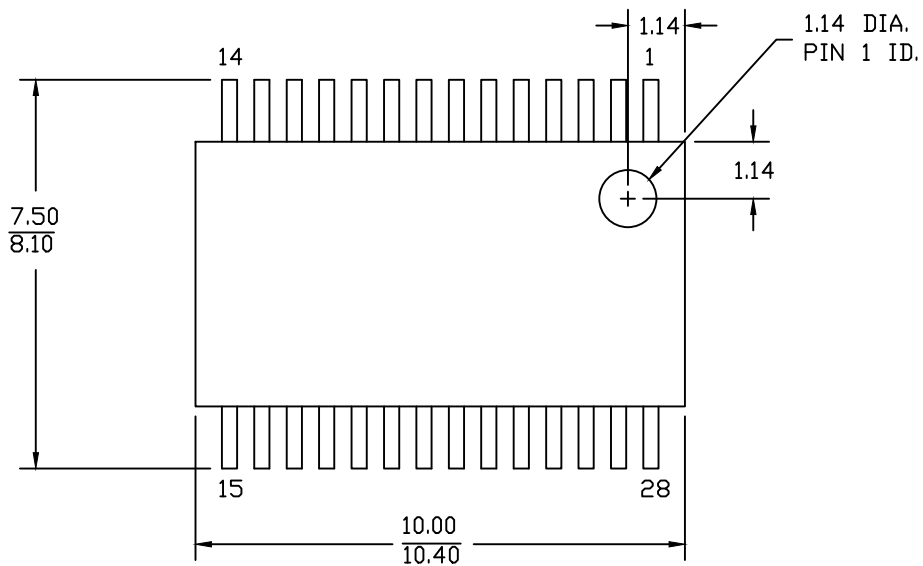
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

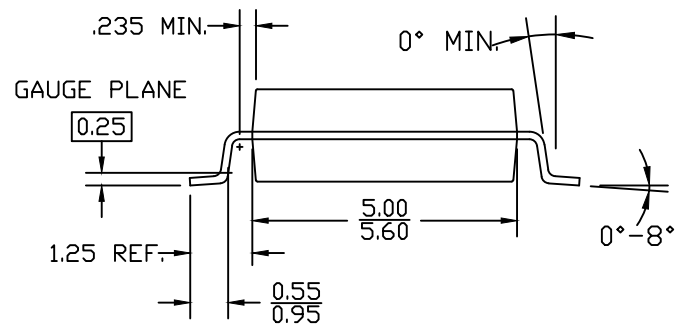
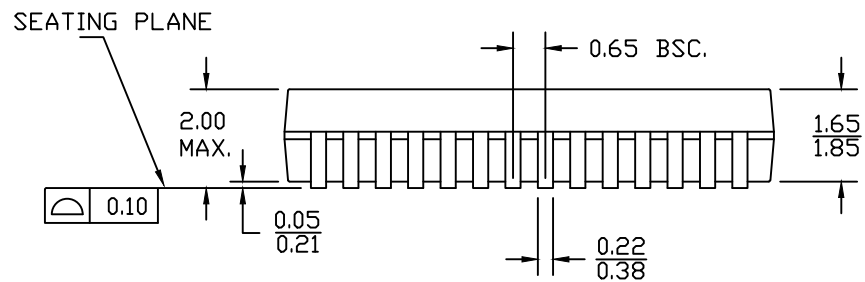
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

28 Lead (10.2 X 5.3mm) SSOP



DIMENSIONS IN MILLIMETERS MIN.
MAX.



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PACKAGE CODE(S)

SP28



TITLE PACKAGE OUTLINE, 28 LEAD SSOP 10.2 X 5.3 X 2.0 MM SP28

SPEC NO. 51-85079

REV *G

SCALE

SHEET 1 OF 2

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
ALL	-	**	1578	NEW RELEASE	04/02/96	N/A
ALL	-	*A	47614	ADD DIMENSION NOTE	12/11/96	N/A
ALL	-	*B	49425	CHG. TITLE/ ADD LEAD COPLANARITY	06/11/97	N/A
ALL	-	*C	111255	DEL. TOP BODY WIDTH DIM./ ADD BTM DIM./CHG. DIM. IN CONFORMANCE TO OSE PKG. OUTL.	10/25/01	N/A
ALL	-	*D	2835564	Changed template, & title from 28LD (210 MIL) SSOP PKG. OUTLINE to PACKAGE OUTLINE, 28LD SSOP 210 MILS 028.21.	12/28/09	QAD
ALL	-	*E	3230060	NO CHANGE. SUNSET REVIEW.	04/16/11	TSV
ALL	-	*F	4585887	Sunset Review, Changed drawing template.	12/03/14	QAD
ALL	-	*G	6893258	Sunset review. Rename drawing title format to "PACKAGE OUTLINE, 28 LEAD SSOP 10.2 X 5.3 X 2.0 MM SP28". Remove obsolete spec 01-06001 as reference.	06/05/20	RODP



TITLE PACKAGE OUTLINE, 28 LEAD SSOP 10.2 X 5.3 X 2.0 MM SP28

SPEC NO. 51-85079 REV *G

SCALE SHEET 2 OF 2

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